

Title (en)  
METHOD AND DEVICE FOR ENCAPSULATING MICROSTRUCTURES

Title (de)  
VERFAHREN UND VORRICHTUNG ZUM EINKAPSELN VON MIKROSTRUKTUREN

Title (fr)  
PROCEDE ET DISPOSITIF D'ENCAPSULATION DE MICROSTRUCTURES

Publication  
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Application  
**EP 09740426 A 20090731**

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Abstract (en)  
[origin: WO2010012966A2] The present invention relates to a method for encapsulating structures (11) (typically MEMS structures) supported by a carrier substrate (12) (typically made of glass or silicon), which method comprises: application, on the carrier substrate (12), of at least one cover (7) supported by a mould (1, 2, 6), the mould comprising a catching layer (6), each cover (7) being in contact with the catching layer (6); then fastening of at least one cover (7) onto the carrier substrate (12); and then separation of the mould (1, 2, 6) from the at least one cover (7). The catching layer (6) comprises a fluoropolymer. Preferably, the mould (1, 2, 6) is separated from the at least one cover (7) by mechanical means, by pulling the mould (1, 2, 6) away from the at least one cover (7). Thus, the mould (1) can be reused, which considerably simplifies encapsulating operations carried out on an industrial scale.

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